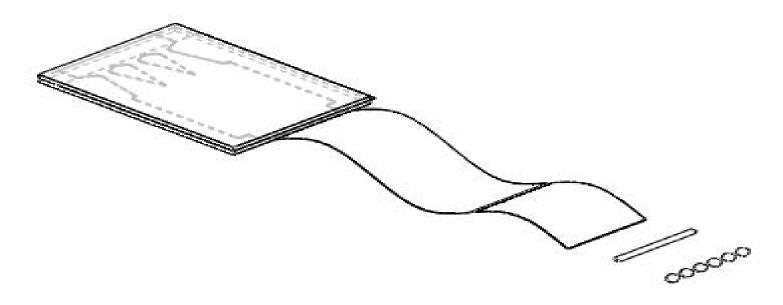
MEMS Technology for Jet Fuel Atomization

James Nabity, Sean Rooney TDA Research, Inc



Turbine Engine Technology Symposium 2004 Fuel-Injector Technology Workshop 2 September 2004



maintaining the data needed, and c including suggestions for reducing	lection of information is estimated to completing and reviewing the collect this burden, to Washington Headqu uld be aware that notwithstanding ar DMB control number.	ion of information. Send comments a arters Services, Directorate for Infor	regarding this burden estimate mation Operations and Reports	or any other aspect of the s, 1215 Jefferson Davis	is collection of information, Highway, Suite 1204, Arlington	
REPORT DATE 2		2. REPORT TYPE		3. DATES COVERED 00-00-2004 to 00-00-2004		
4. TITLE AND SUBTITLE		5a. CONTRACT NUMBER				
MEMS Technology for Jet Fuel Atomization				5b. GRANT NUMBER		
				5c. PROGRAM ELEMENT NUMBER		
6. AUTHOR(S)				5d. PROJECT NUMBER		
				5e. TASK NUMBER		
				5f. WORK UNIT NUMBER		
7. PERFORMING ORGANIZATION NAME(S) AND ADDRESS(ES) TDA Research Inc,12345 West 52nd Avenue,Wheat Ridge,CO,80033-1916				8. PERFORMING ORGANIZATION REPORT NUMBER		
9. SPONSORING/MONITORING AGENCY NAME(S) AND ADDRESS(ES)				10. SPONSOR/MONITOR'S ACRONYM(S)		
				11. SPONSOR/MONITOR'S REPORT NUMBER(S)		
12. DISTRIBUTION/AVAIL Approved for publ	LABILITY STATEMENT ic release; distributi	on unlimited				
13. SUPPLEMENTARY NO The original docum	otes nent contains color i	mages.				
14. ABSTRACT						
15. SUBJECT TERMS						
16. SECURITY CLASSIFICATION OF:			17. LIMITATION OF ABSTRACT	18. NUMBER OF PAGES	19a. NAME OF	
a. REPORT unclassified	b. ABSTRACT unclassified	c. THIS PAGE unclassified	ADSTRACT	21	RESPONSIBLE PERSON	

Report Documentation Page

Form Approved OMB No. 0704-0188

Acknowledgements

- ONR Dr. Chris Brophy
- AFOSR Dr. Mitat Birkan
- AF Dr. Balu Sekar
- University of Colorado
 - Dr. John Daily, Professor
 - Mr. Gopi Krishnan, PhD candidate



Outline

- Objective
- Atomizer technologies
- MEMS atomizer
- Approach to design, build and test
- Conclusions



Objective

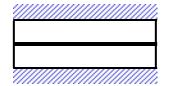
- Develop a MEMS atomizer to produce small (<50μm) droplets
 - improve gas turbine flameholding
 - reduce emissions



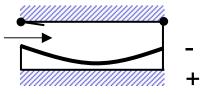
Baseline Technologies

Air blast / air assist (Many types; internal mixed type shown here)

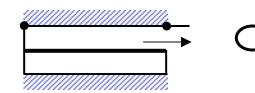
 Others: Simple Orifice, Poppet Orifice, Ultrasonic, Electrostatic Charge, Inkjet



Initial state



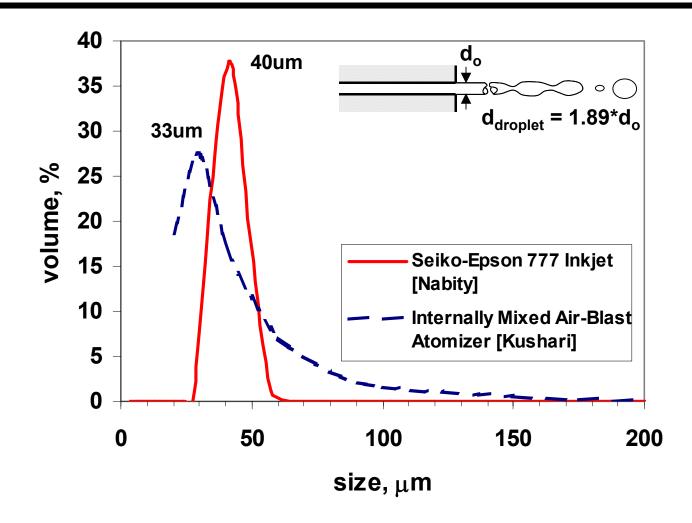
Applied DC voltage draws down the pressure plate or diaphragm



Remove voltage to release diaphragm and eject droplet



Droplet Size Measurements

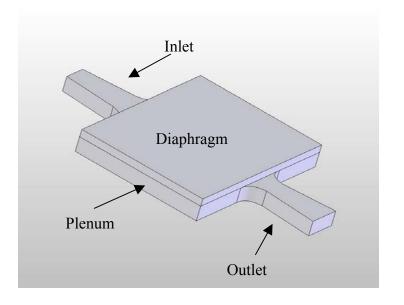




A. Kushari, Y. Neumeier, O. Israeli, E. Lubarsky, and B.T. Zinn, "Internally Mixed Liquid Injector for Active Control of Atomization Process," Journal of Propulsion and Power, Vol. 17, No. 4, July-August 2001.

The Basic Design

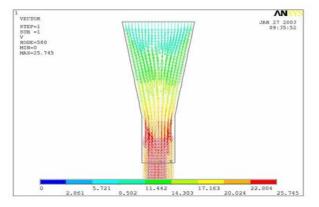
- Electrostatically actuated diaphragm pump with passive valves:
 - •Electrostatic for high displacement/low power.
 - •Passive valves for simplicity.

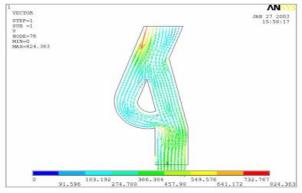


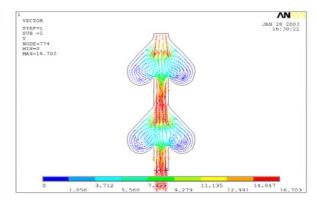


What is Important?

- Need high pump efficiency: $\eta = \frac{Q_{net}}{Q_{ideal}}$
- Valves are critical







Dielectric – cleanliness is everything

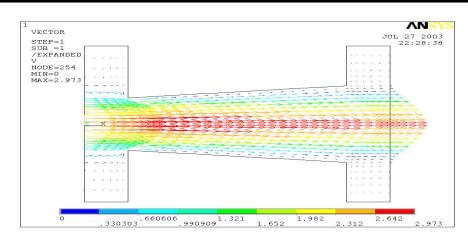


Approach

- Analytical & numerical performance modeling
 - Fuel ejection & droplet formation
 - Micropump operation (especially, the valving)
 - Stiction
- Fabrication
 - Materials, processes and assembly
- Engine integration
- Testing



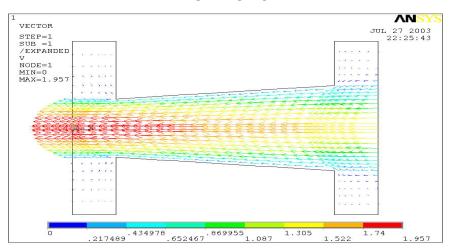
Fluidic Valve Performance Evaluation



Flow rectification

Steady 2.2 Periodic 1.4

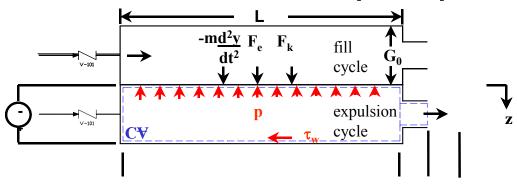
forward



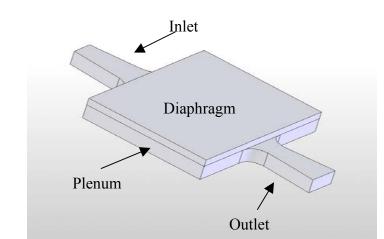


Performance Modeling

TDA's Quasi 1-D Micropump Model



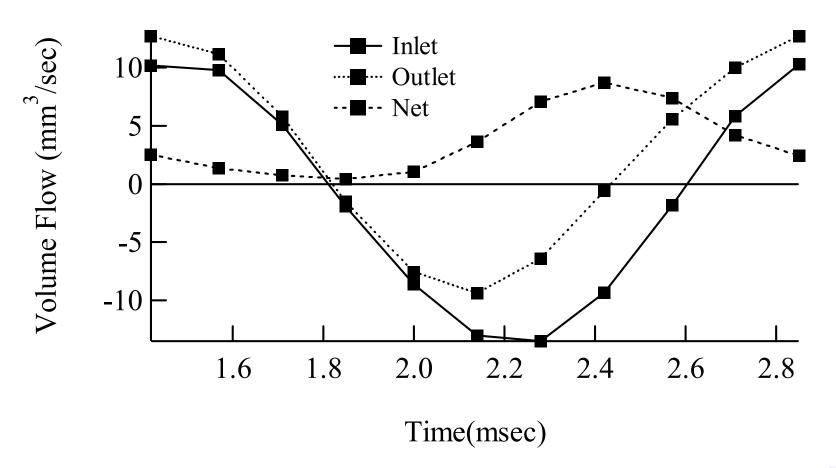
ANSYS fully coupled modeling



$$L_{diaph} = 1000 \ \mu m$$
 $t_{diaph} = 10 \ \mu m$
 $t_{plenum} = 100 \ \mu m$
 $t_{passages} = 100 \ \mu m$
 $L_{passages} = 330 \ \mu m$
 $W_{inpassages} = 66.7 \ \mu m$
 $\alpha_{valve} = 5 \ degrees$

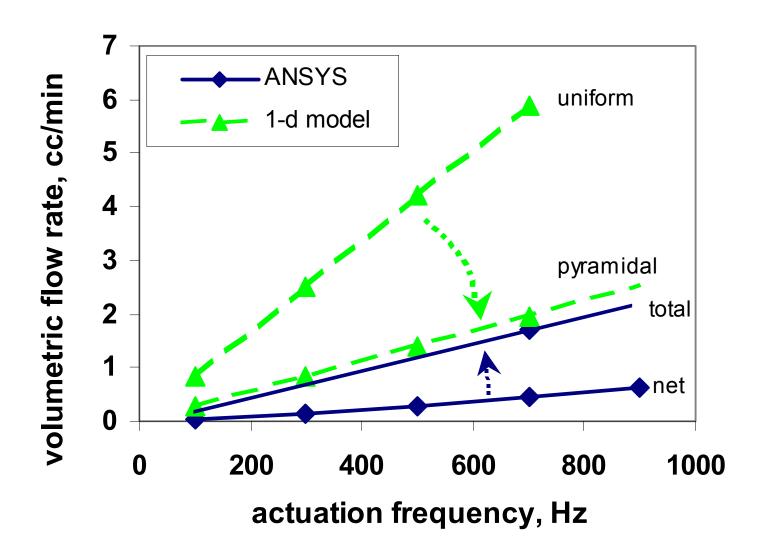


ANSYS Results (30um sinusoidal deflection at 700 Hz)





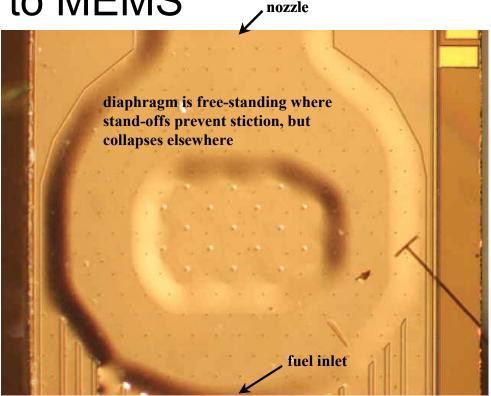
Model Performance Predictions





Stiction

Nemesis to MEMS



 Therefore, use Mastrangelo elastocapillary & peel numbers

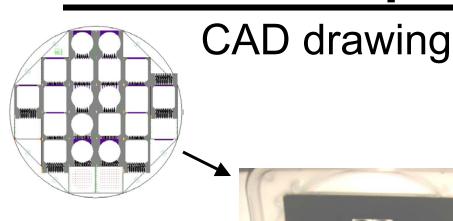


Materials

- Silicon most commonly used material
 - 3-inch SSP wafer costs about \$10
 - -<1800°F
- Silicon carbide 20X the cost, but good to 2900°F
- Silicon carbide nitride also expensive, but highest temperature and strength



Wafer Level Microprocessing



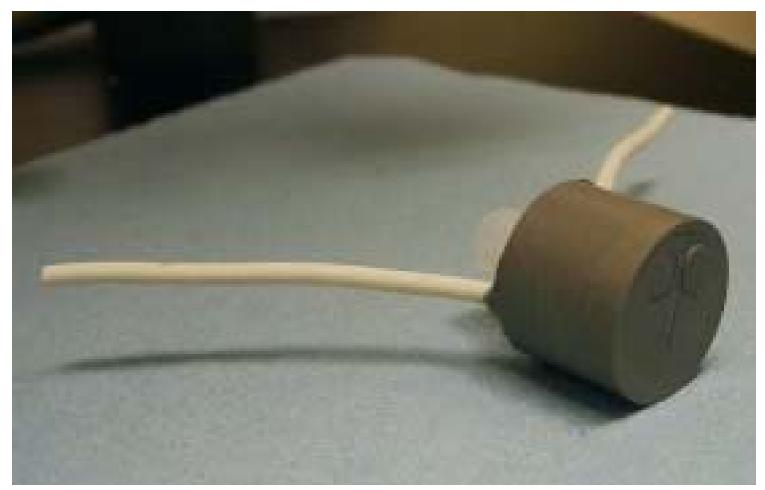
Mask



Pattern & etch

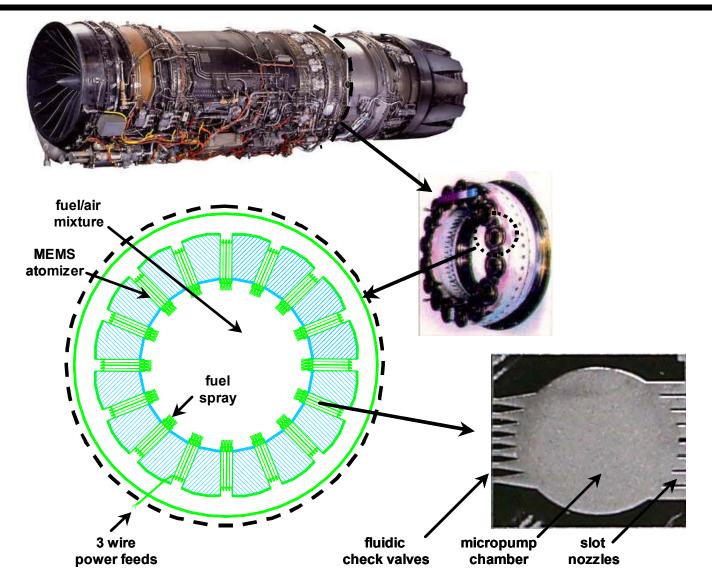


Assembly & Packaging



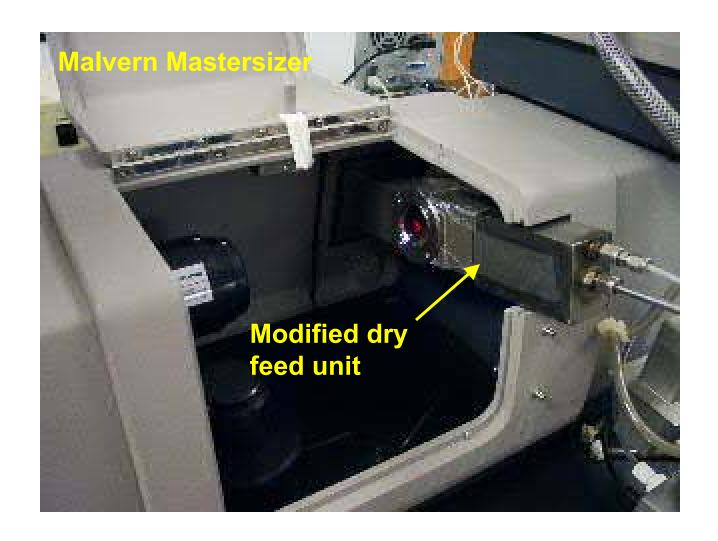


Gas Turbine





Test Setup





Conclusions

- Analytical & computational tools Developed
- Design completed
- MEMS fabrication processes defined
- Atomizers built
- Testing underway



Contact Info

Mr. James Nabity, Principal Investigator TDA Research, Inc. 12345 W 52nd Ave Wheat Ridge, CO 80033

(303)940-2313

nabity@tda.com

